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Physical Design Automation for High-Density 3D Power Module Layout Synthesis and Optimization

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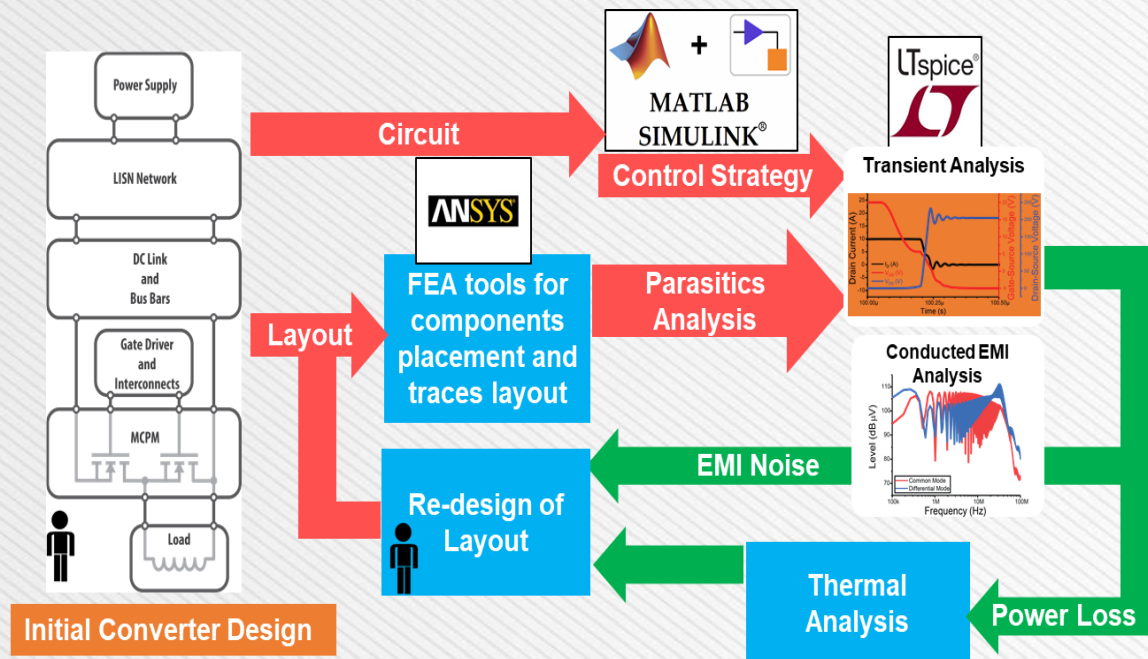
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Traditional vs. Automatic Design Flow

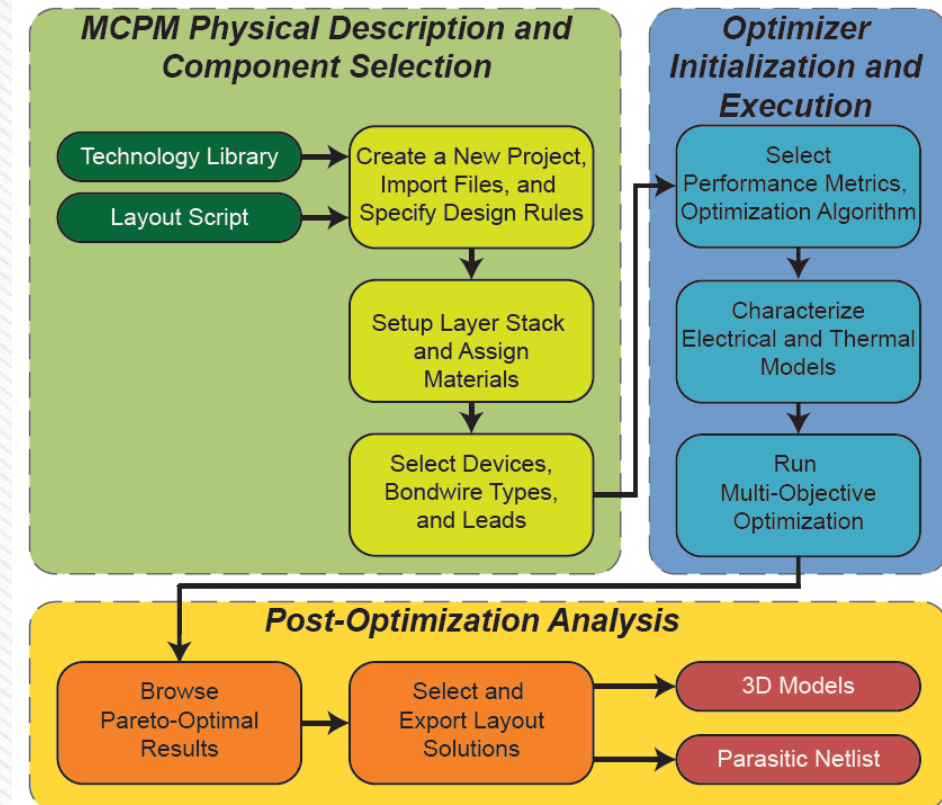
Manual Design Flow

- Tedious and computationally expensive design flow



Our Approach: PowerSynth

- A software tool for the layout synthesis and optimization of multi-chip power modules [1].



[1] T. M. Evans *et al.*, "PowerSynth: A Power Module Layout Generation Tool," in *IEEE Transactions on Power Electronics*, 2019.



PowerSynth 2 Introduction



❑ Already demonstrated:

- 2D and 2.5D heterogeneous power module optimization capability.

❑ To increase the power density :

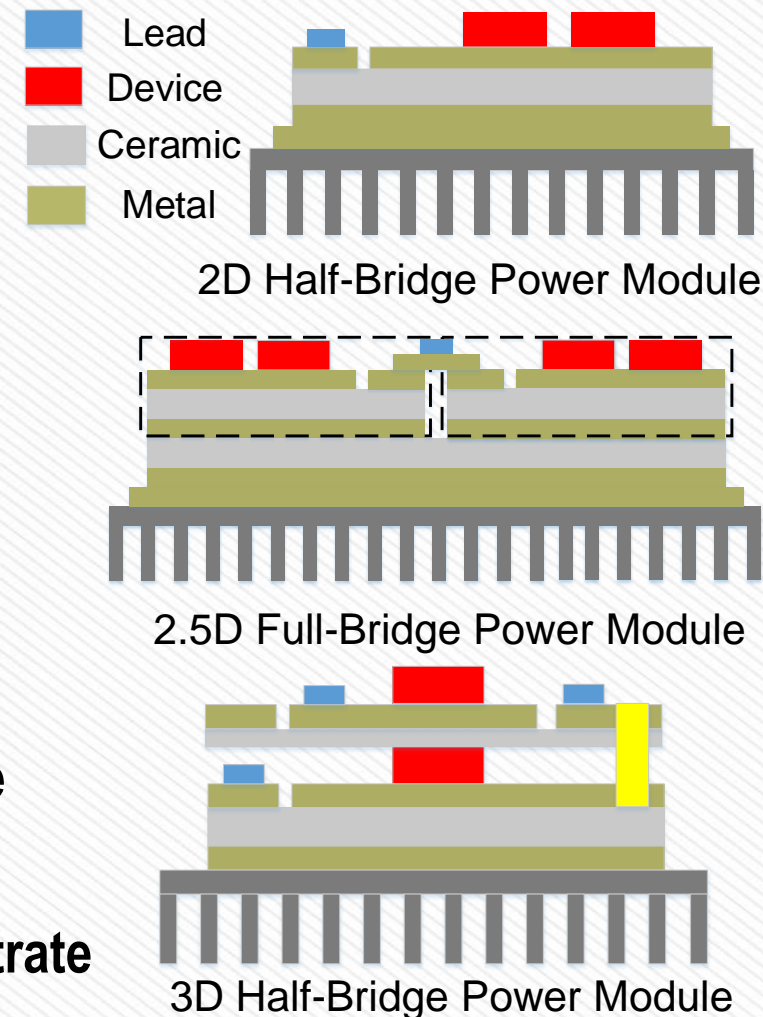
- 3D heterogeneous power modules optimization are obvious.

❑ Feature Update:

- 3D power module layout generation and optimization.

❑ Three types of layouts handled by PowerSynth:

- 2D layout: One device layer with routing layers on the same substrate
- 2.5D layout: Multiple 2D designs connected on a supporting 2D plane
- 3D layout: Multiple device layers stacked vertically on the same substrate





PowerSynth 2 Methodology



Layout Representation:

- Multiple 2D layers connected with vertical vias

Data Structure and Algorithms:

- Hierarchical tree structure of corner-stitched planes

Layout Generation:

- Hierarchical constraint graphs
 - Guarantee DRC-clean solutions

Layout Optimization:

- Efficient models
 - Electrical/thermal/mechanical
- Optimization algorithms
 - Tradeoff among multi-objectives

High-level pseudocode:

```

Read Input Script
Create a root node
Create group of layers connected with same via

```

For each group

```

  Create a sub-root in the tree containing via location

```

For each layer

```

  Create HCS, VCS
  Create and Evaluate HCG, VCG

```

For each ancestor from leaf to root

```

  Perform bottom-up constraint propagation
  Evaluate root node and compute available space

```

For each sub-tree from root to leaf

```

  Perform top-down location propagation

```

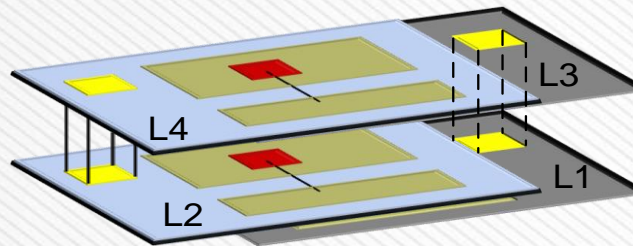
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Evaluate independent nodes

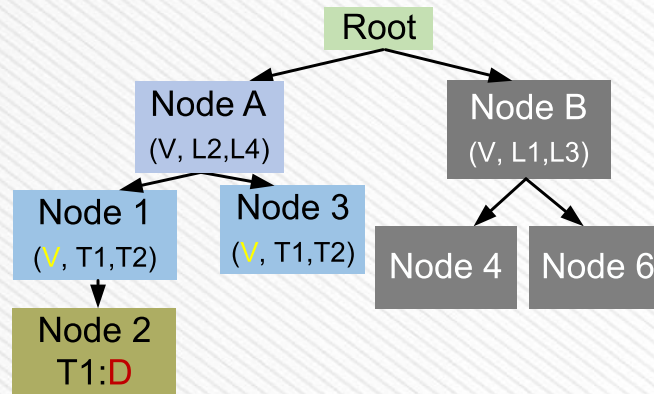
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HCS/VCS: Horizontal/Vertical Corner Stitch
HCG/VCG: Horizontal/Vertical Constraint Graph

Via (V)
 Trace (T)
 Device (D)



Sample 3D structure

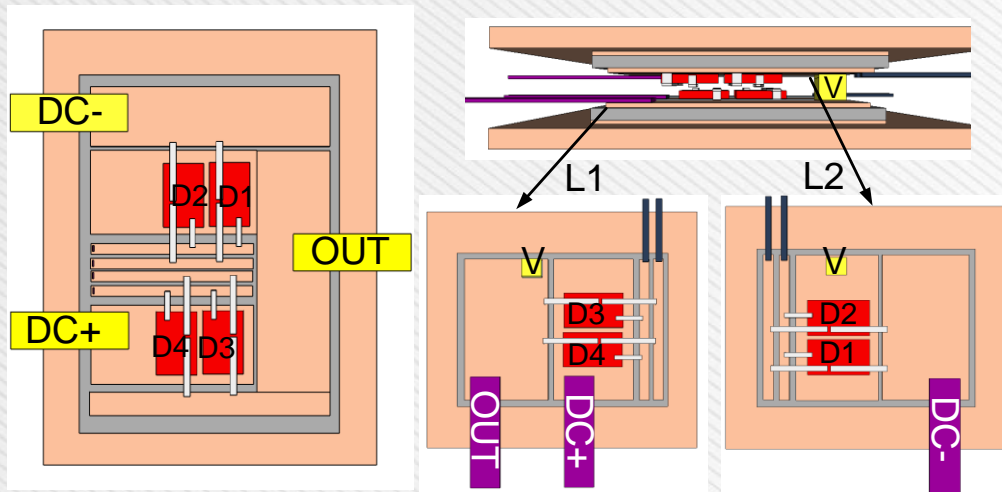


Tree representation

3D Layout Generation Results

2D vs. 3D Performance Comparison:

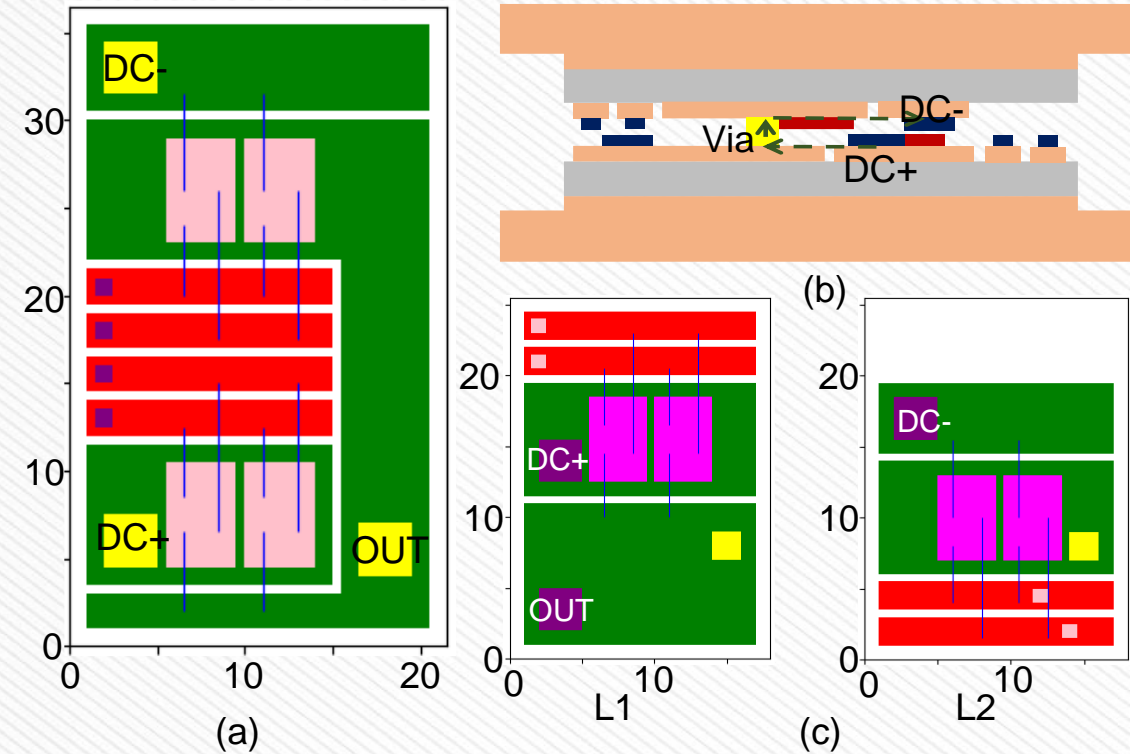
Initial layout:



Half-bridge MCPM: 2D structure (left), 3D structure (right)

Performance Metric	2D	3D
Loop Inductance (@100 KHz)	15.93 nH	6.104 nH
Max Temperature	332.15 K	370.29 K (single-side cooling)
		328.38 K (dual-side cooling)

Min-sized Result:



(a) 2D layout (b) 3D power loop, (c) high-side (Layer 1) and low-side (Layer 2) layers of 3D layout

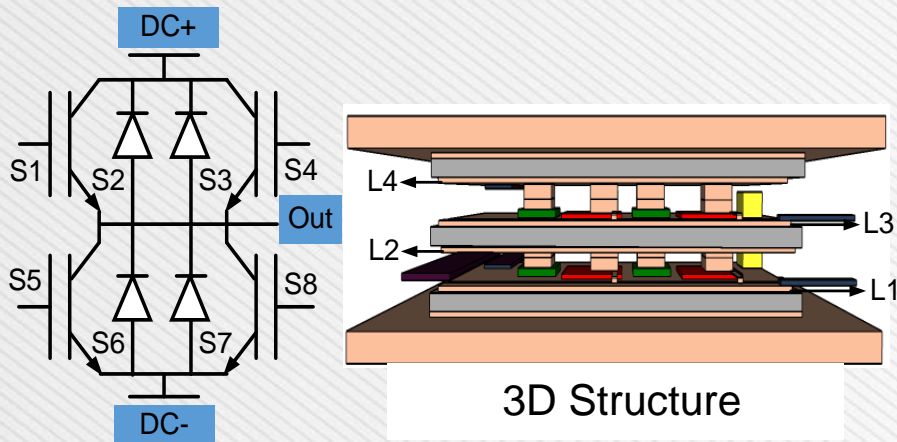


3D Layout Optimization Results



3D Layout Optimization:

Initial Layout:



Electro-thermal evaluation:

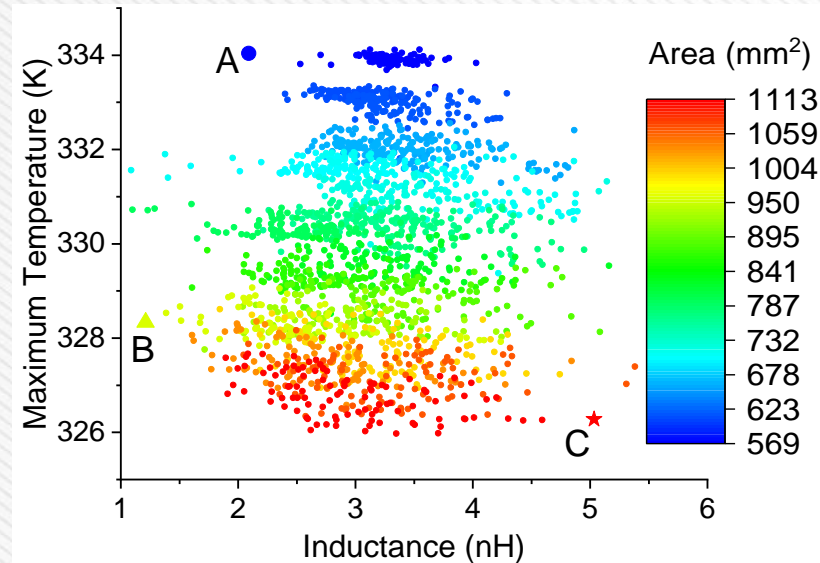
- ParaPower [2] thermal model
- FastHenry electrical model

Optimization:

- 2400 solutions are generated
- 0.08s per solution generated

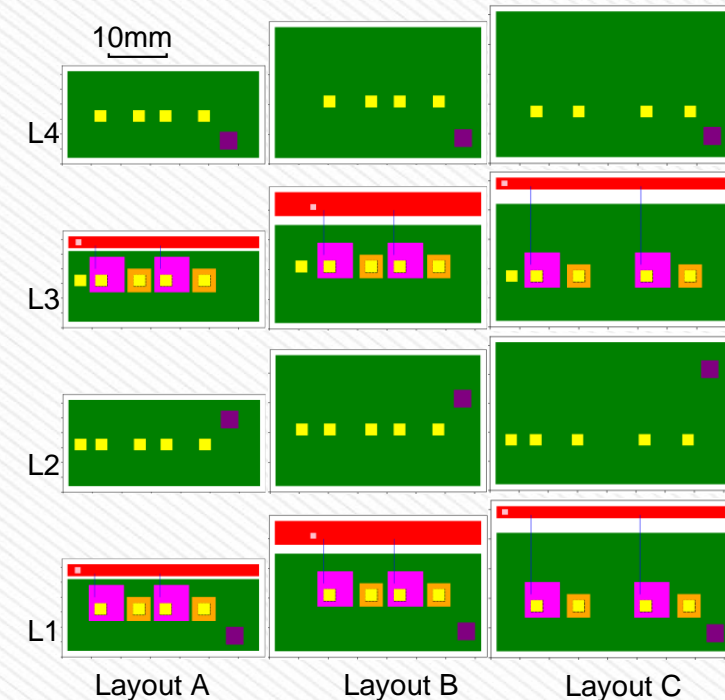
[2] "ARL ParaPower" :<https://github.com/USArmyResearchLab/ParaPower>

Solution Space:



Performance values

ID	L (nH)	T (K)	Size (mm ²)
A	1.44	334.11	34.5 × 16.5
B	1.22	328.13	37.0 × 24.0
C	2.43	324.62	42.0 × 26.5



Three selected layouts



Conclusions and Future Works



Conclusions:

- Generic and efficient algorithms to handle both intra-layer and inter-layer connections
- Able to handle arbitrary number of layers in an efficient manner.
- This methodology is generic and can be extended towards cabinet-level optimization.

Future Work:

- Update the algorithm for generic 3D layout cases and validate through measurements.
- Customized optimization algorithm to find a better tradeoff among multiple objectives.
- PowerSynth v2.0 release

